

PRODUCT SPECIFICATION

L297B-SR

Wi-Fi Dual-band 2x2 11ac+ Bluetooth 5.0

Combo Module

Version:v1.2



L297B-SR Module Datasheet

Ordering Information	Part NO.	Description
	FGL297BSRX-00	NXP88W8997, b/g/n/ac, Wi-Fi+BLE5.0, 2T2R, 13X15mm, SDIO/ UART, PCB version V1.0

Customer: _____

Customer P/N: _____

Signature: _____

Date: _____

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CONTENTS

1. General Description.....	5
1.1 Introduction.....	5
1.2 Description.....	5
2. Features.....	6
3. Block Diagram.....	7
4. General Specification.....	7
4.1 2.4GHz WI-FI Specification.....	7
4.2 5GHz WI-FI Specification.....	8
4.3 Bluetooth Specification.....	9
5. ID setting information.....	9
6. Pin Definition.....	10
6.1 Pin Outline.....	10
6.2 Pin Definition details.....	10
7. Electrical Specifications.....	12
7.1 Host Interface Specifications.....	12
7.1.1 SDIO Specifications.....	12
7.1.2 Default Speed, High-Speed Modes.....	12
7.1.3 SDR12, SDR25, SDR50 Modes (up to 100 MHz) (1.8V).....	13
7.1.4 SDR104 Mode (208 MHz) (1.8V).....	14
7.1.5 DDR50 Mode (50 MHz) (1.8V).....	15
7.2 High-Speed UART Specifications.....	17
7.2.1 UART Timing Diagram.....	17
7.2.2 UART Baud Rates Supported.....	17
8. Size reference.....	18
8.1 Module Picture.....	18
8.2 Marking Description.....	18
8.3 Physical Dimensions.....	19
8.4 Layout Recommendation.....	20
9. The Key Material List.....	21
10. Reference Design.....	22
11. Recommended Reflow Profile.....	23
12. Package.....	24
12.1 Reel.....	24
12.2 Packaging Detail.....	24
13. Moisture sensitivity.....	25

Revision History

Version	Date	Contents of Revision Change	Prepared	Checked	Approved
V1.0	2021/11/19	New version	FC	Tzq	Qjp
V1.1	2022/01/19	Add Module picture Revision pin definition Add marking description	FC	Tzq	Qjp
V1.2	2022/02/15	Update ping outline	FC		

1. General Description

1.1 Introduction

This document is to specify the product requirements for 802.11a/b/g/n/ac and Bluetooth 5.0 SDIO&UART module. This module based on NXP(MARVELL) 88W8997 chipset that complied with IEEE 802.11a, IEEE 802.11b, IEEE 802.11g, IEEE 802.11n, IEEE 802.11ac standard from 2.4~2.5GHz and 5.15GHz ~ 5.85GHz, and it also can be used to provide up to 11Mbps for IEEE 802.11b, 54Mbps for IEEE 802.11a and IEEE 802.11g, 150Mbps for 802.11n and 866.7Mbps for IEEE 802.11ac to connect your wireless LAN.

1.2 Description

Model Name	L297B-SR
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 13 x 15 x2.3 mm
Wi-Fi Interface	Support SDIO V2.0/3.0
BT Interface	UART/SDIO
OS supported	Android /Linux/ Win CE /iOS /XP/WIN7/WIN10
Operating temperature	-30°C to 85°C
Storage temperature	-55°C to 125°C

2. Features

General

- Compatible with IEEE 802.11a standard to provide wireless 54Mbps data rate
- Compatible with IEEE 802.11b standard to provide wireless 11Mbps data rate
- Compatible with IEEE 802.11g standard to provide wireless 54Mbps data rate
- Compatible with IEEE 802.11n standard to provide wireless 150Mbps data rate
- Compatible with IEEE 802.11ac standard to provide wireless 866.7Mbps data rate
- Supports TKIP/WEP, AES/CCMP, AES/CMAC, AES/GCMP and WAPI enhanced security

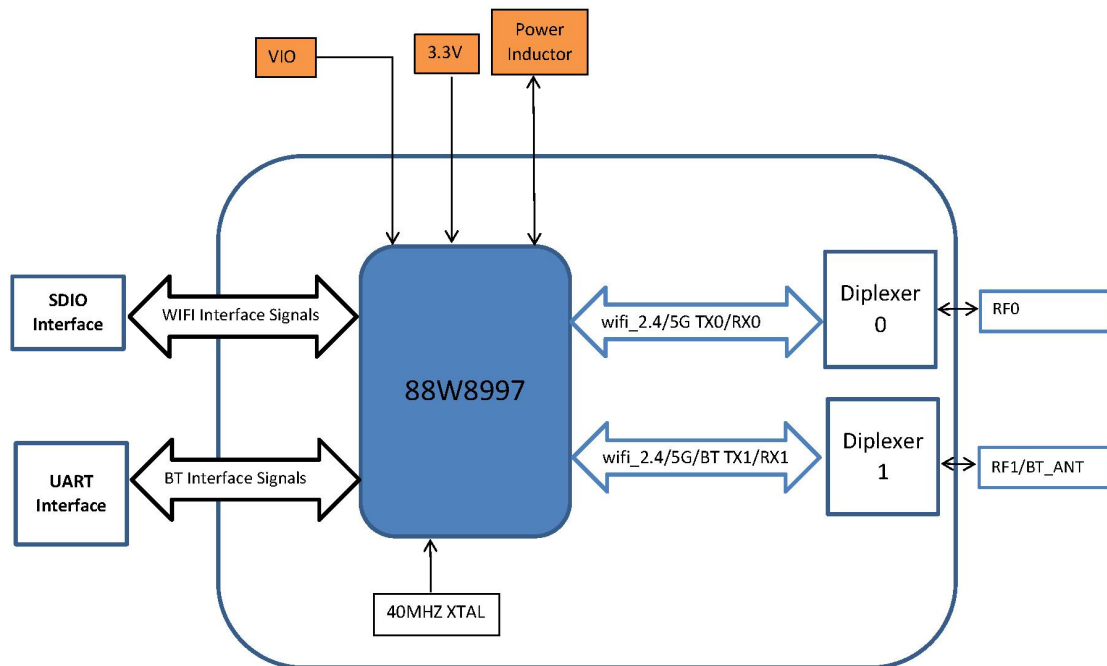
Host Interface

- SDIO 2.0/3.0 Interface for WLAN
- SDIO Interface or High-Speed UART Interface for Bluetooth
- HSF compliant

Bluetooth Features

- Bluetooth 5.0 compliant
- Supports Bluetooth classic (BDR/EDR)
- Supports Bluetooth Low Energy (BLE)

3. Block Diagram



4. General Specification

4.1 2.4GHz WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n Wi-Fi compliant	
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4 GHz ISM Band)	
Number of Channels	2.4GHz: Ch1 ~ Ch14	
Test Items	Typical Value	EVM
Output Power	802.11b /11Mbps : 16dBm ± 2 dB	EVM ≤ -10dB
	802.11g /54Mbps : 15dBm ± 2 dB	EVM ≤ -25dB
	802.11n /MCS7 : 14dBm ± 2 dB	EVM ≤ -28dB
Spectrum Mask	Meet with IEEE standard	
Freq. Tolerance	± 20ppm	
Receive Sensitivity (11b,20MHz) @8% PER	- 11Mbps PER @ -83 dBm	≤-76

Receive Sensitivity (11g,20MHz) @10% PER	- 54Mbps	PER @ -74 dBm	≤-65
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=7	PER @ -68 dBm	≤-64
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=7,	PER @ -66 dBm	≤-61

4.2 5GHz WI-FI Specification

Feature	Description		
WLAN Standard	IEEE 802.11a/n/ac, Wi-Fi compliant		
Frequency Range	4.900 GHz ~ 5.845 GHz (5.0 GHz ISM Band)		
Number of Channels	5.0GHz: Please see the table1		
Modulation	802.11a/n : 64-QAM,16-QAM, QPSK, BPSK 802.11ac : 256-QAM, 64-QAM,16-QAM, QPSK, BPSK		
Test Items	Typical Value		EVM
Output Power	802.11a /11Mbps	: 15dBm ± 2 dB	EVM ≤ -10dB
	802.11n /MCS7(HT20)	: 14dBm ± 2 dB	EVM ≤ -25dB
	802.11n /MCS7(HT40)	: 14dBm ± 2 dB	EVM ≤ -28dB
	802.11ac/MCS8(VHT20)	: 11 dBm ± 2 dB	EVM ≤ -30dB
	802.11ac/MCS9(VHT40)	: 11 dBm ± 2 dB	EVM ≤ -32dB
	802.11ac/MCS9(VHT80)	: 11 dBm ± 2 dB	EVM ≤ -32dB
Spectrum Mask	Meet with IEEE standard		
Receive Sensitivity (11a,20MHz) @8% PER	- 54Mbps	PER @ -71 dBm	≤-65
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=7	PER @ -68 dBm	≤-64
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=7,	PER @ -66 dBm	≤-61
Receive Sensitivity (11ac,20MHz)@10% PER	- MCS=8	PER @ -64 dBm	≤-59
Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=9	PER @ -58 dBm	≤-54
Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=9	PER @ -55 dBm	≤-51

4.3 Bluetooth Specification

Feature	Description		
General Specification			
Bluetooth Standard	Bluetooth V5.0		
Host Interface	UART		
Frequency Band	2402 MHz ~ 2480 MHz		
Number of Channels	79 channels for BDR+EDR 40 channels for BLE		
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK		
RF Specification			
	Min(dBm)	Typical(dBm)	Max(dBm)
BDR Output Power		8	
BLE Output Power		8	
	Min	Typical	IEEE
Sensitivity @ BER=0.1% for GFSK (1Mbps)		-86	-70
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)		-86	-70
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)		-80	-70
Sensitive @PER=30.8% for BLE		-90	-70
Maximum Input Level	GFSK (1Mbps):-20dBm		
	$\pi/4$ -DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

5. ID setting information

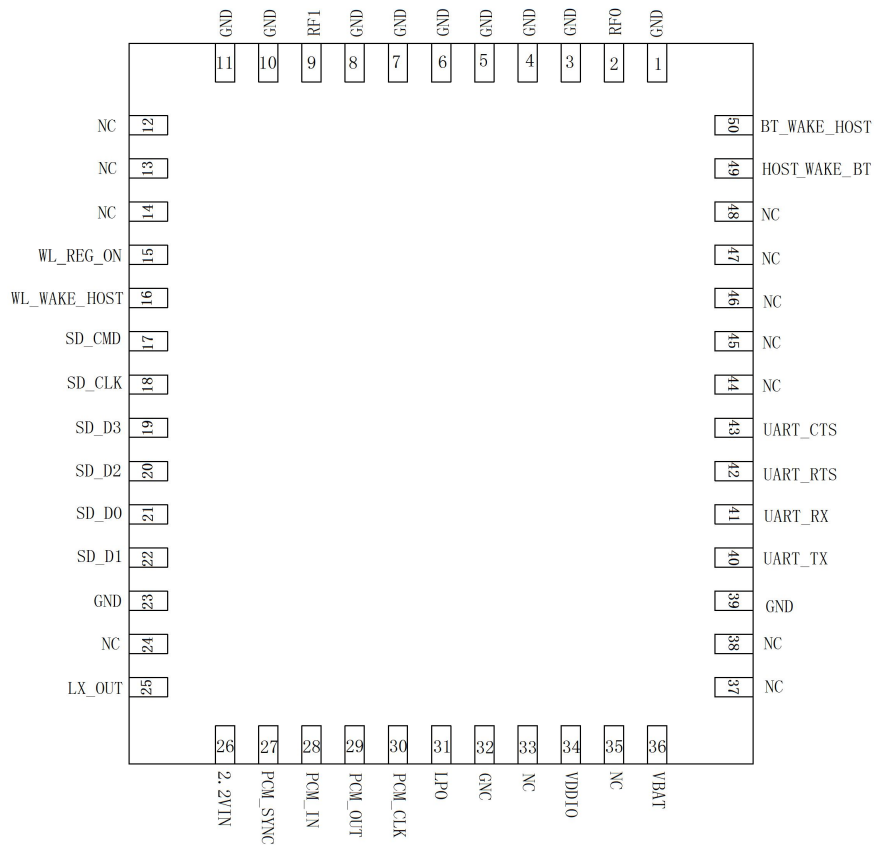
WI-FI

Vendor ID	0x02DF
Product ID	0x9141

6. Pin Definition

6.1 Pin Outline

< TOP VIEW >



6.2 Pin Definition details

NO.	Name	Type	Description	Voltage
1	GND		Ground connections	
2	RF0		WIFI_RF0	
3~8	GND		Ground connections	
9	RF1		WIFI_RF1/BT_RF	
10	GND		Ground connections	

11	GND		Ground connections	
12~14	NC		Floating (NC)	
15	WL_REG_ON	I	Full Power-Down When the host reboot, this pin should power down (active low)	VDDIO
16	WL_WAKE_HOST	O	WLAN to wake up HOST	VDDIO
17	SD_CMD	I/O	SDIO command line	VDDIO
18	SD_CLK	I/O	SDIO clock line	VDDIO
19	SD_D3	I/O	SDIO data line 3	VDDIO
20	SD_D2	I/O	SDIO data line 2	VDDIO
21	SD_D0	I/O	SDIO data line 0	VDDIO
22	SD_D1	I/O	SDIO data line 1	VDDIO
23	GND		Ground connections	VDDIO
24	NC		Floating (NC)	
25	LX_OUT	O	Need to connect a Power Inductor and then connect to pin26 (2.2V)	VDDIO
26	2.2VIN	I	DCDC_IN (2.2V)	
27	PCM_SYNC	I/O	PCM Sync	
28	PCM_IN	I/O	PCM Input	
29	PCM_OUT	I/O	PCM Output	
30	PCM_CLK	I/O	PCM Clock	
31	LPO	I	Crystals of up to 32.768 K	
32	GND		Ground connections	
33	NC		Floating (NC)	
34	VDDIO		Only control the Voltage of SDIO, Can be 1.8V or 3.3V	
35	NC		Floating (NC)	
36	VBAT		VDD3.3V	
37	NC		Floating (NC)	
38	NC		Floating (NC)	
39	GND		Ground connections	
40	UART_Tx		UART_Tx	
41	UART_Rx		UART_Rx	
42	UART_RTS		UART_RTS	
43	UART_CTS		UART_CTS	
44	NC		Floating (NC)	
45	NC		Floating (NC)	

46	NC		Floating (NC)	
47	NC		Floating (NC)	
48	NC		Floating (NC)	
49	HOST_WAKE_BT	I	Host device to wake up Bluetooth	
50	BT_WAKE_HOST	O	Bluetooth device to wake up host	

P:POWER I:INPUT O:OUTPUT VDDIO:3.3V

7. Electrical Specifications

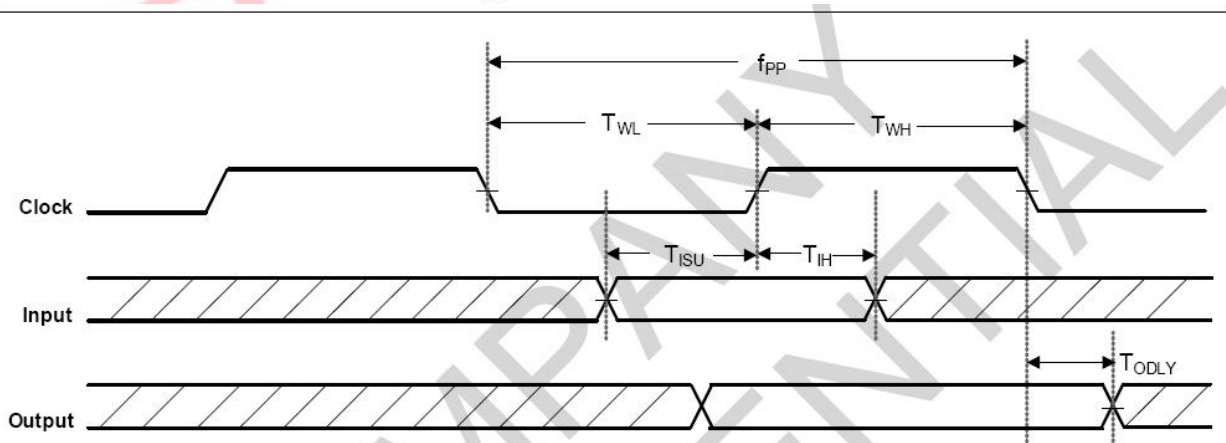
7.1 Host Interface Specifications

7.1.1 SDIO Specifications

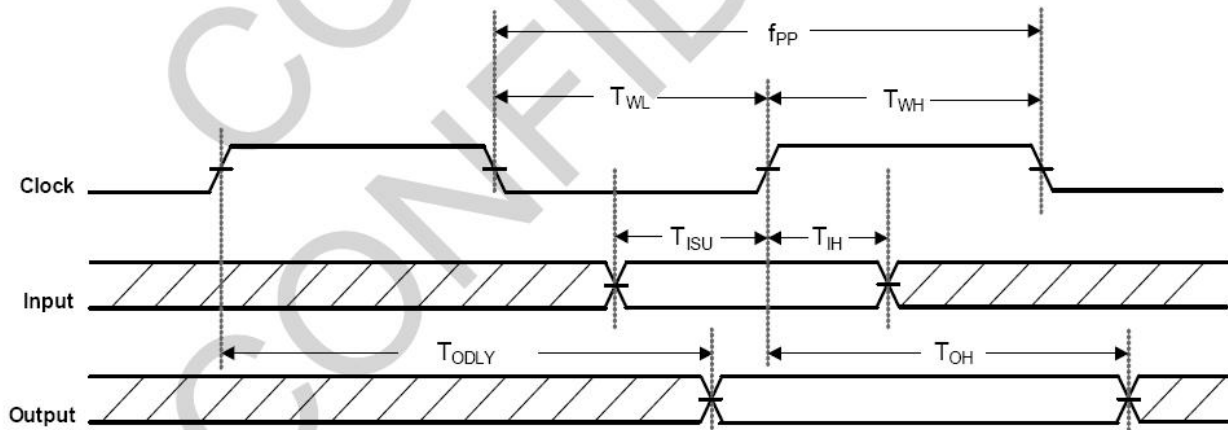
The SDIO host interface pins are powered from the VIO_SD voltage supply

7.1.2 Default Speed, High-Speed Modes

SDIO Protocol Timing Diagram—Default Speed Mode (3.3V)



SDIO Protocol Timing Diagram—High-Speed Mode (3.3V)



SDIO Timing Data—Default Speed, High-Speed Modes (3.3V)1, 2

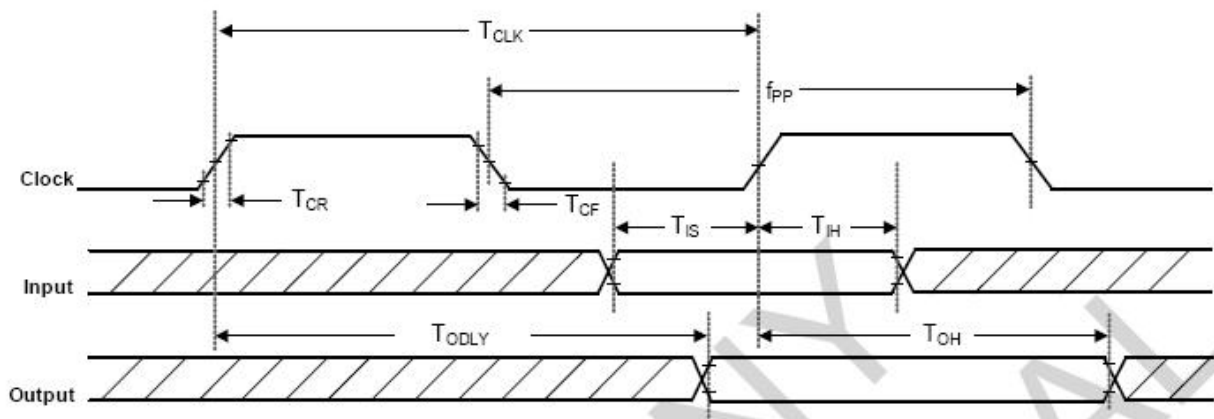
NOTE: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency	Normal	0	--	25	MHz
		High-speed	0	--	50	MHz
T_{WL}	Clock low time	Normal	10	--	--	ns
		High-speed	7	--	--	ns
T_{WH}	Clock high time	Normal	10	--	--	ns
		High-speed	7	--	--	ns
T_{ISU}	Input setup time	Normal	5	--	--	ns
		High-speed	6	--	--	ns
T_{IH}	Input hold time	Normal	5	--	--	ns
		High-speed	2	--	--	ns
T_{ODLY}	Output delay time	Normal	--	--	14	ns
	CL ≤ 40 pF (1 card)	High-speed	--	--	14	ns
T_{OH}	Output hold time	High-speed	2.5	--	--	ns

1. For SDIO 2.0 running at 50 MHz clock frequency, only 1.8V is supported.
2. For SDIO 2.0 running at 25 MHz clock frequency, 1.8V or 3.3V is supported.

7.1.3 SDR12, SDR25, SDR50 Modes (up to 100 MHz) (1.8V)

SDIO Protocol Timing Diagram—SDR12, SDR25, SDR50 Modes (up to 100 MHz) (1.8V)



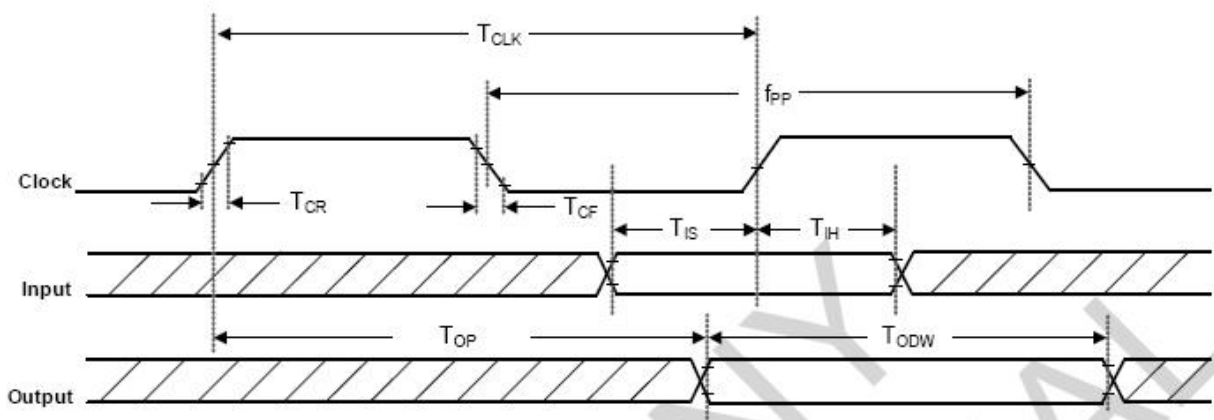
SDIO Timing Data—SDR12, SDR25, SDR50 Modes (up to 100 MHz) (1.8V)

NOTE: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency	SDR12/25/50	25	--	100	MHz
T_{IS}	Input setup time	SDR12/25/50	3	--	--	ns
T_{IH}	Input hold time	SDR12/25/50	0.8	--	--	ns
T_{CLK}	Clock time	SDR12/25/50	10	--	40	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 2$ ns (max) at 100 MHz $C_{CARD} = 10$ pF	SDR12/25/50	--	--	$0.2 \cdot T_{CLK}$	ns
T_{ODLY}	Output delay time $C_L \leq 30$ pF	SDR12/25/50	--	--	7.5	ns
T_{OH}	Output hold time $C_L = 15$ pF	SDR12/25/50	1.5	--	--	ns

7.1.4 SDR104 Mode (208 MHz) (1.8V)

SDIO Protocol Timing Diagram—SDR104 Mode (208 MHz)



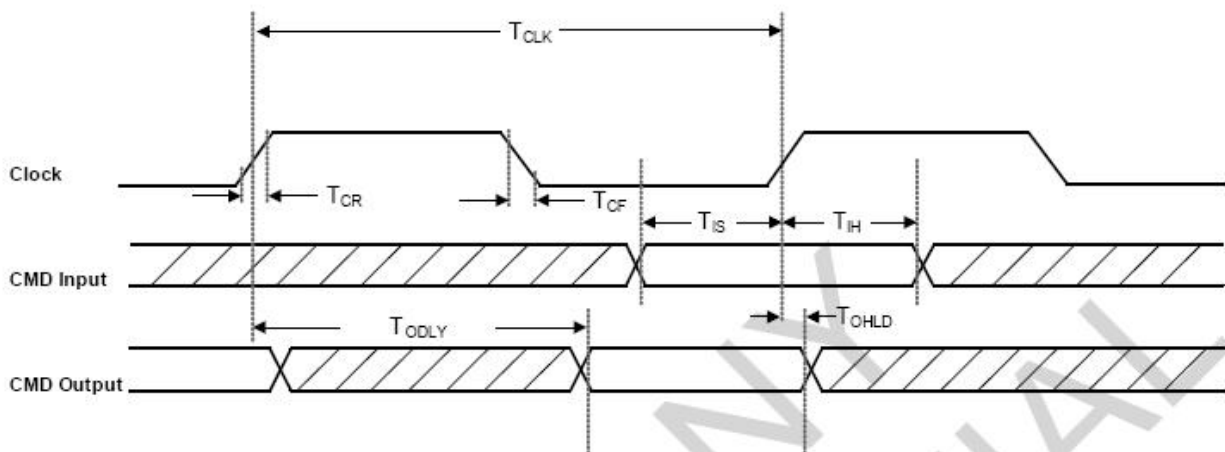
SDIO Timing Data—SDR104 Mode (208 MHz)

NOTE: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

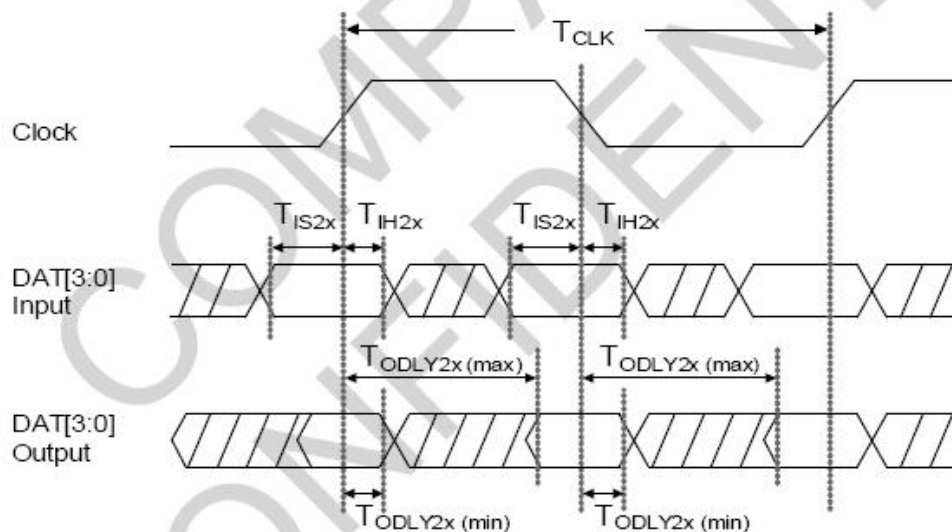
Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency	SDR104	0	--	208	MHz
T_{IS}	Input setup time	SDR104	1.4	--	--	ns
T_{IH}	Input hold time	SDR104	0.8	--	--	ns
T_{CLK}	Clock time	SDR104	4.8	--	--	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 0.96$ ns (max) at 208 MHz $C_{CARD} = 10$ pF	SDR104	--	--	$0.2 \cdot T_{CLK}$	ns
T_{OP}	Card output phase	SDR104	0	--	10	ns
T_{ODW}	Output timing of variable data window	SDR104	2.88	--	--	ns

7.1.5 DDR50 Mode (50 MHz) (1.8V)

SDIO CMD Timing Diagram—DDR50 Mode (50 MHz)



SDIO DAT[3:0] Timing Diagram—DDR50 Mode1 (50 MHz)



1. In DDR50 mode, DAT[3:0] lines are sampled on both edges of the clock (not applicable for CMD line).

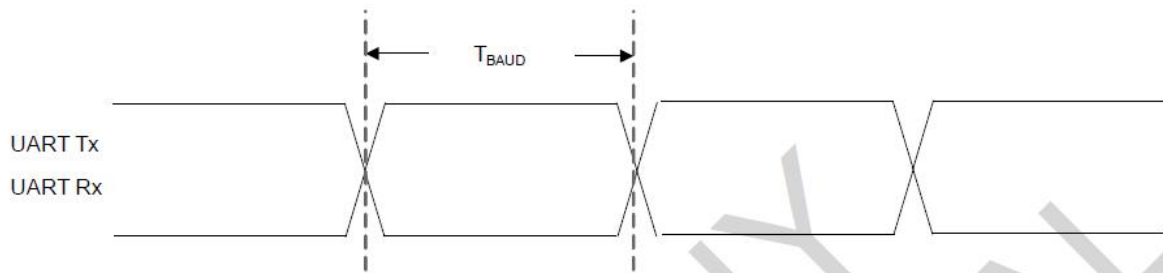
SDIO Timing Data—DDR50 Mode (50 MHz)

NOTE: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Units
Clock						
T _{CLK}	Clock time 50 MHz (max) between rising edges	DDR50	20	--	--	ns
T _{CR} , T _{CF}	Rise time, fall time T _{CR} , T _{CF} < 4.00 ns (max) at 50 MHz C _{CARD} = 10 pF	DDR50	--	--	0.2*T _{CLK}	ns
Clock Duty	--	DDR50	45	--	55	%
CMD Input (referenced to clock rising edge)						
T _{IS}	Input setup time C _{CARD} ≤ 10 pF (1 card)	DDR50	6	--	--	ns
T _{IH}	Input hold time C _{CARD} ≤ 10 pF (1 card)	DDR50	0.8	--	--	ns
CMD Output (referenced to clock rising edge)						
T _{ODLY}	Output delay time during data transfer mode C _L ≤ 30 pF (1 card)	DDR50	--	--	13.7	ns
T _{OHLd}	Output hold time C _L ≥ 15 pF (1 card)	DDR50	1.5	--	--	ns
DAT[3:0] Input (referenced to clock rising and falling edges)						
T _{IS2x}	Input setup time C _{CARD} ≤ 10 pF (1 card)	DDR50	3	--	--	ns
T _{IH2x}	Input hold time C _{CARD} ≤ 10 pF (1 card)	DDR50	0.8	--	--	ns
DAT[3:0] Output (referenced to clock rising and falling edges)						
T _{ODLY2x (max)}	Output delay time during data transfer mode C _L ≤ 25 pF (1 card)	DDR50	--	--	7.0	ns
T _{ODLY2x (min)}	Output hold time C _L ≥ 15 pF (1 card)	DDR50	1.5	--	--	ns

7.2 High-Speed UART Specifications

7.2.1 UART Timing Diagram



UART Timing Data1

Symbol	Parameter	Condition	Min	Typ	Max	Units
T_{BAUD}	Baud rate	40 MHz input clock	250	--	--	ns

1. The acceptable deviation from the UART Rx target baud rate is $\pm 3\%$.

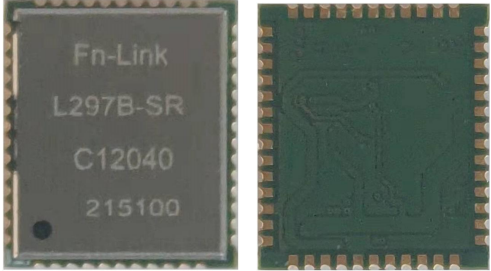
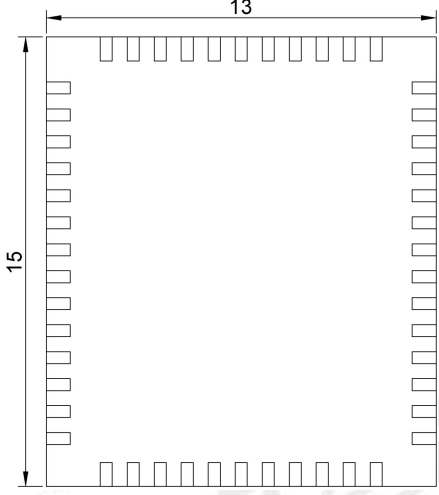

7.2.2 UART Baud Rates Supported

*Note:Default 115200

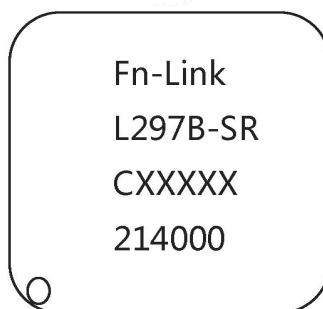
Baud Rate				
1200	38400	460800	1500000	3000000
2400	57600	500000	1843200	3250000
4800	76800	921600	2000000	3692300
9600	115200	1000000	2100000	4000000
19200	230400	1382400	2764800	--

8. Size reference

8.1 Module Picture

<p>L x W : 13 x 15 (+0.3/-0.1) mm</p> 	
<p>H: 2.3 (±0.2) mm</p>	
<p>Weight</p>	<p>TBD</p>

8.2 Marking Description



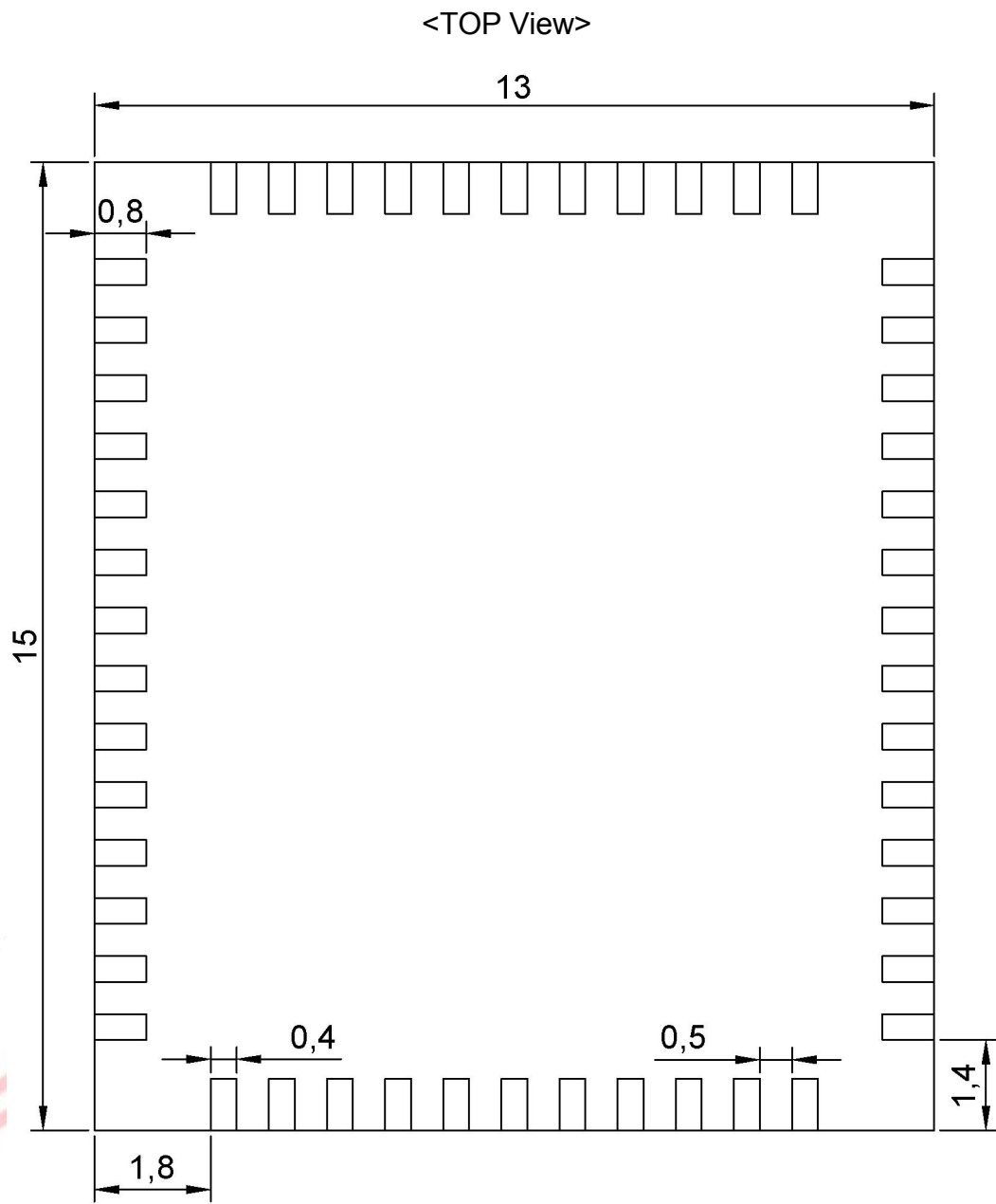
Brand name

Model name

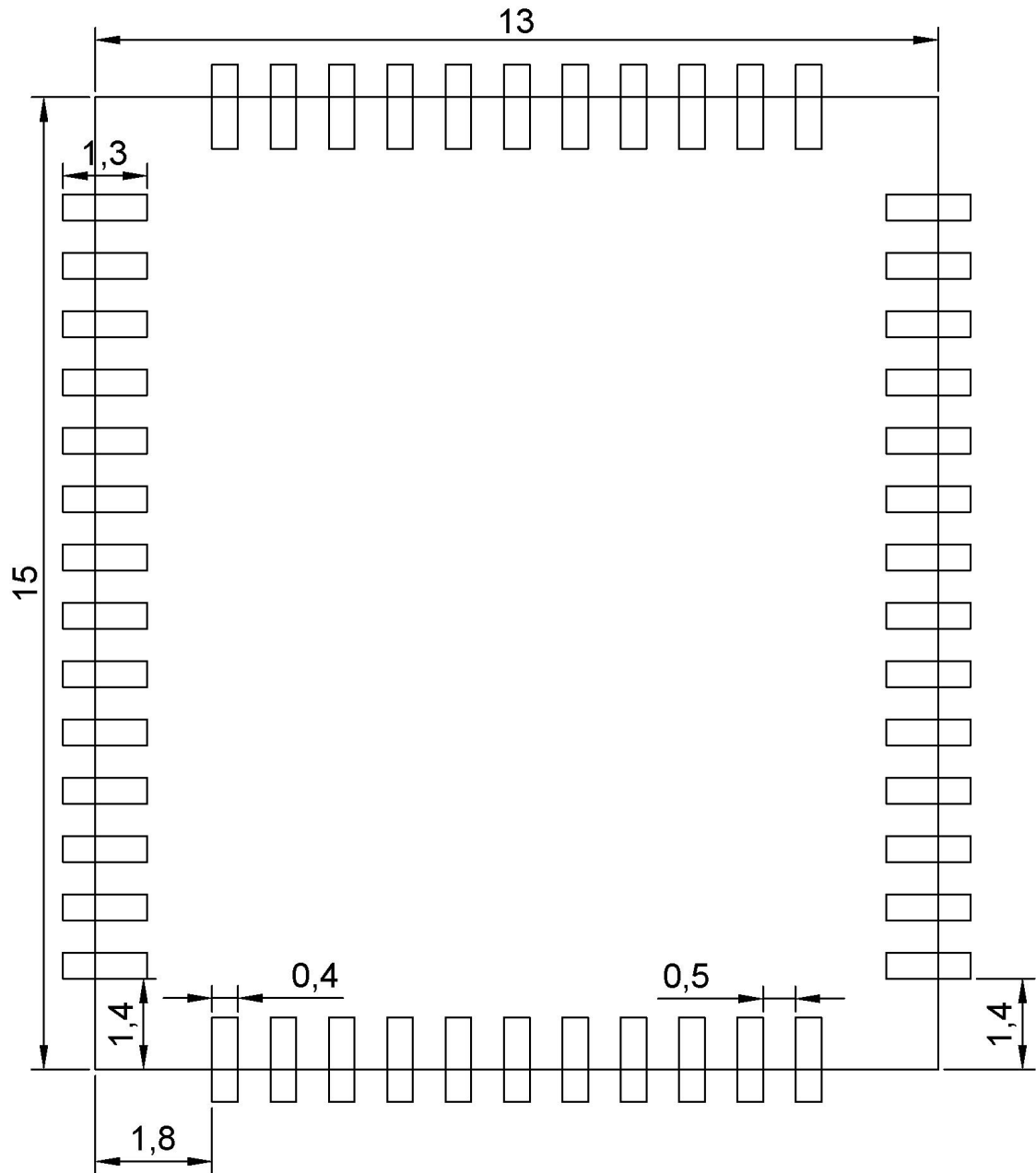
Lot code

Date code

8.3 Physical Dimensions



8.4 Layout Recommendation

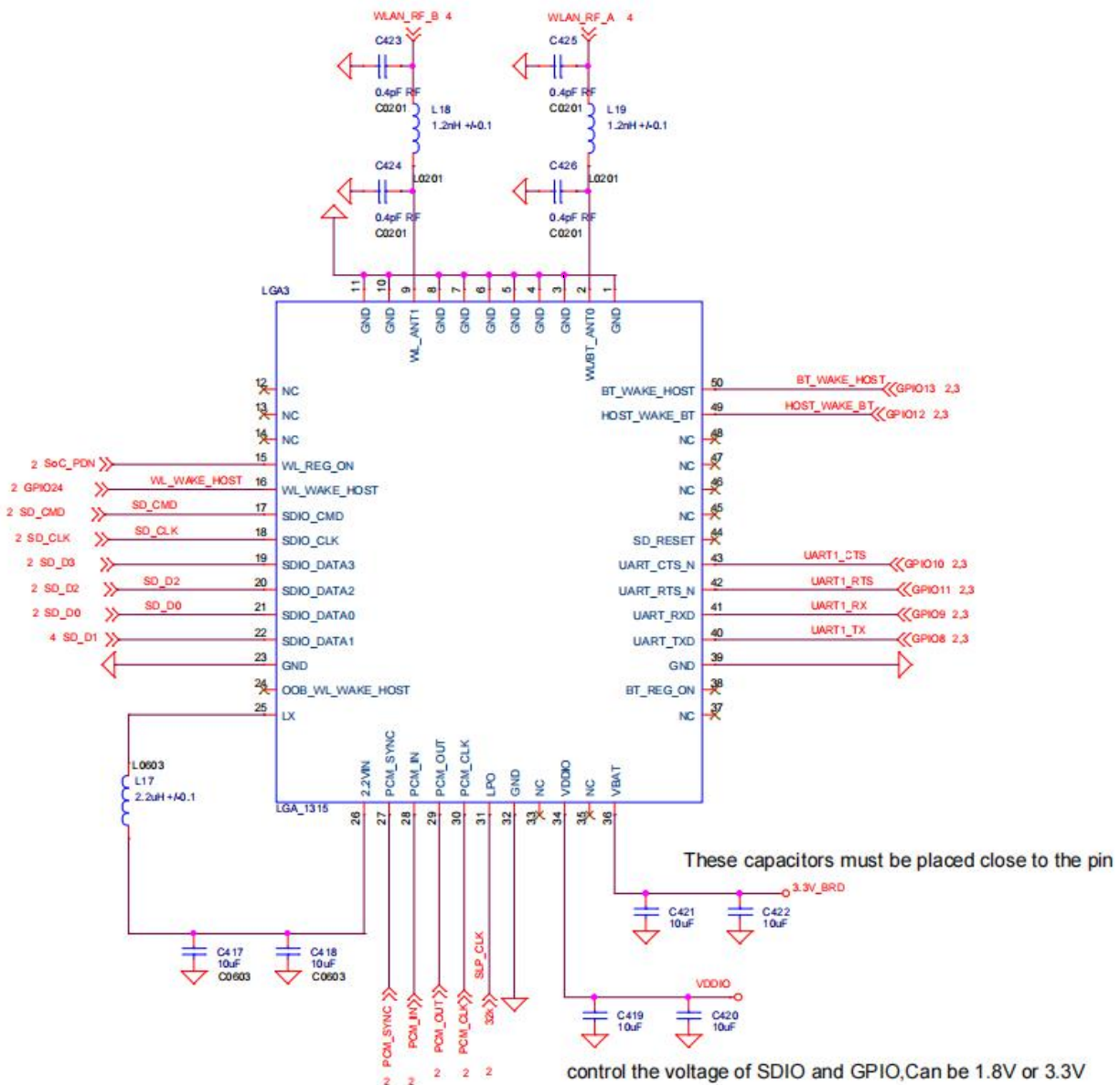


9. The Key Material List

Chipset	NXP 88W8997	NXP
PCB	L297B-SR 深绿色,6L,FR4,13x15x0.8mm	XY-PCB,KX-PCB,SL-PCB,Sunlord
Crystal	2520 40MHz 12pF 10ppm	TST,HOSONIC,TKD,ECEC,JWT
Shielding	L297B-SR Shielding	信太,精力通

FN-LINK 欧智通

10. Reference Design

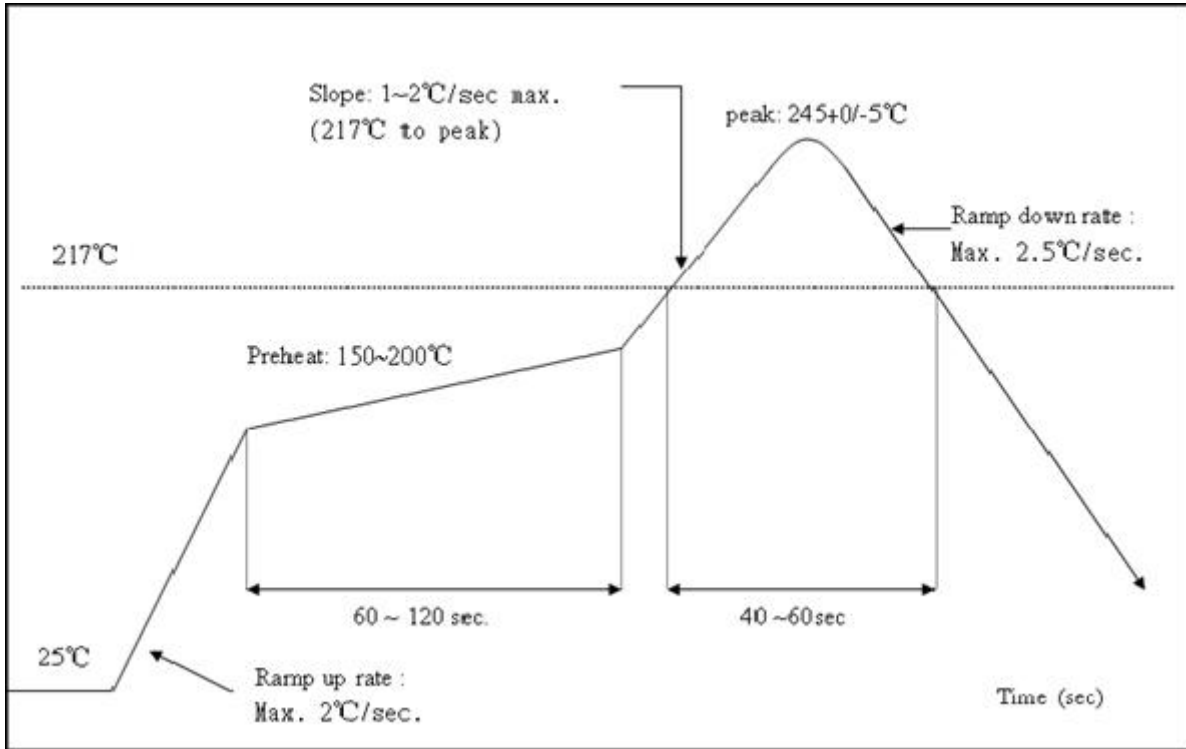


11. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : $<250^{\circ}\text{C}$

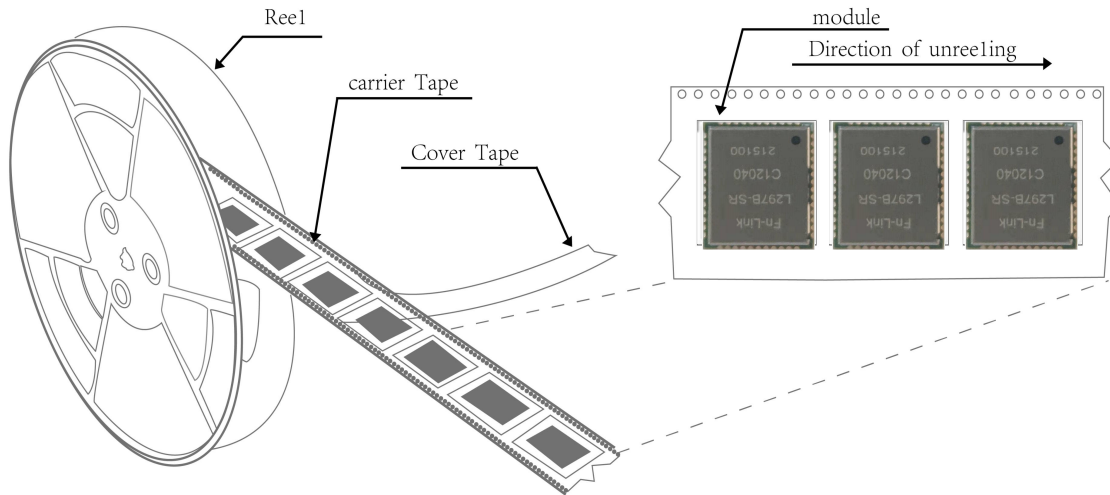
Number of Times : ≤ 2 times



12. Package

12.1 Reel

A roll of 1500pcs



12.2 Packaging Detail

the take-up package



Using self-adhesive tape

Size of black tape: 24mm*32.6m the cover tape :21.3mm*32.6m

Color of plastic disc: blue



NY bag size:460mm*385mm



size : 350*350*35mm



The packing case size:350*210*370mmg

13. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- b) Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
- b) "IPC/JEDEC J-STD-033A paragraph 5.2" is respected
- d) Baking is required if conditions b) or c) are not respected
- e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more

FCC Statement

FCC standards: FCC CFR Title 47 Part 15 Subpart C Section 15.247

External Antenna , 4dBi(Provided by the applicant)

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment. Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:—Reorient or relocate the receiving antenna.—Increase the separation between the equipment and receiver.—Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.—Consult the dealer or an experienced radio/TV technician for help. FCC Radiation Exposure Statement This modular complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter. If the FCC identification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: “Contains Transmitter Module FCC ID: 2AATL-L297BSR Or Contains FCC ID: 2AATL-L297BSR ” When the module is installed inside another device, the user manual of the host must contain below warning statements;

1. This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

2.(1) This device may not cause harmful interference; (2) This device must accept any interference received, including interference that may cause undesired operation. Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radiofrequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

—Reorient or relocate the receiving antenna. —Increase the separation between the equipment and receiver. —Connect the equipment into an outlet on a circuit different from that to which the receiver is connected. —Consult the dealer or an experienced radio/TV technician for help. 2. Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment. The devices must be installed and used in strict accordance with the manufacturer's instructions as described in the user documentation that comes with the product. Any company of the host device which install this modular with modular approval should perform the test of radiated & conducted emission and spurious emission, etc. according to FCC part 15C : 15.247 and 15.209 & 15.207, 15B Class B requirement, Only if the test result comply with FCC part 15C : 15.247 and 15.209 & 15.207, 15B Class B requirement, then the host can be sold legally.

External antenna specification

Antenna manufacturer: RTANT COMMUNICATIONS co.,LTD

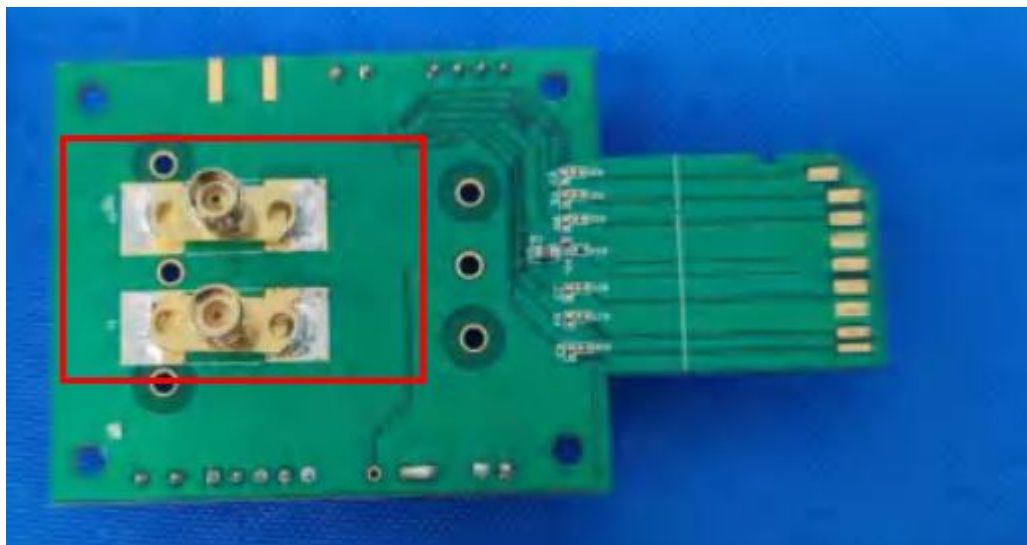
Building E, Shalong Ludlang Industrial Innovation Park, Shatang Industrial Zone,
Houjie Town, Dongguan City

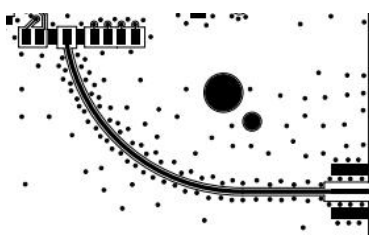
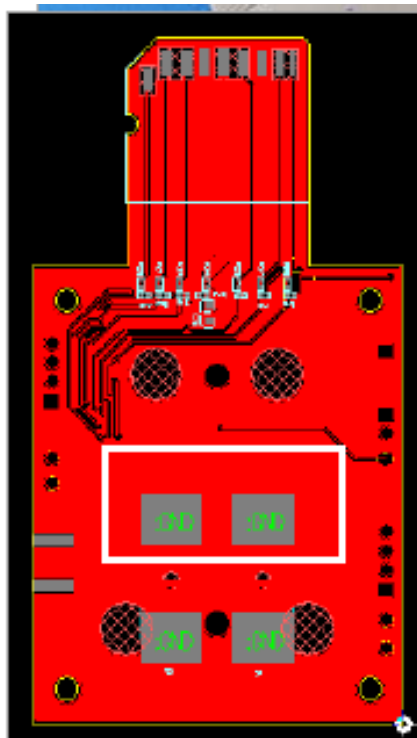
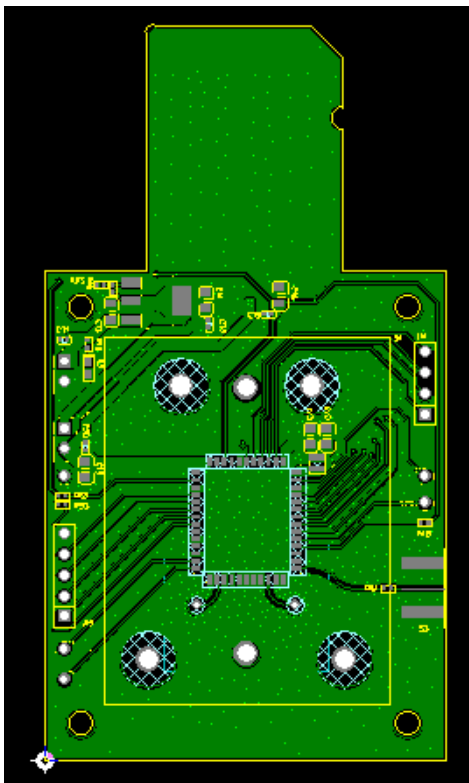
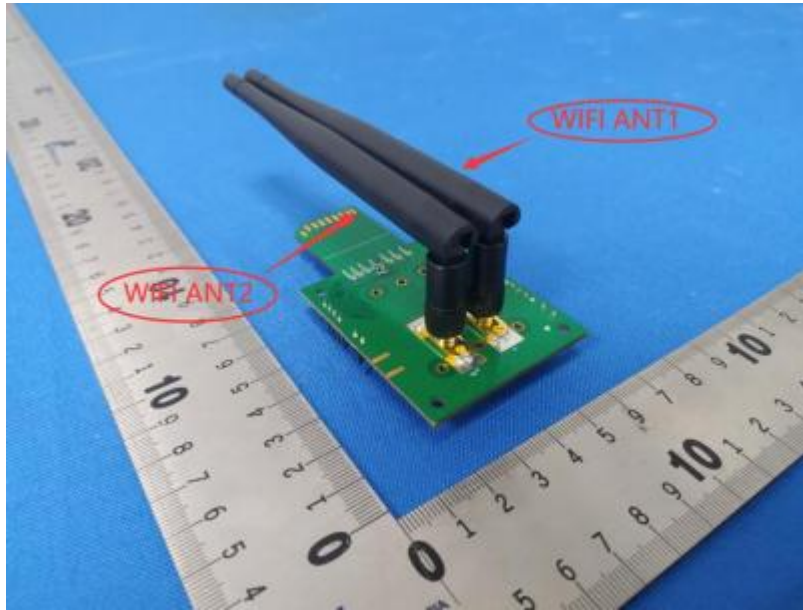


antenna model: External Antenna

Antenna Gain: 4dBi

Please refer to the chart below for PCB size of RF line terminal.





The line between the External antenna and the BT module must be 50 ohm.

